

TOPCon背面细栅浆料
TOPCon Rear-Side Finger Paste

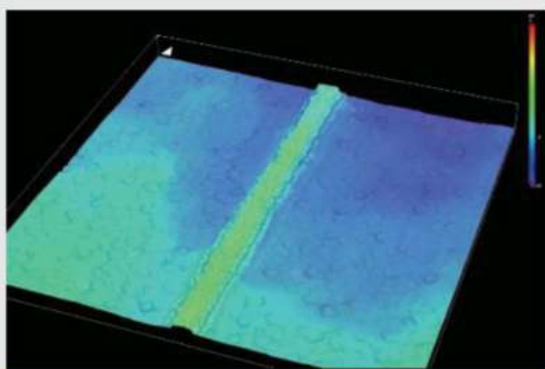
GT90系列
GT90 Series

适用范围
Application

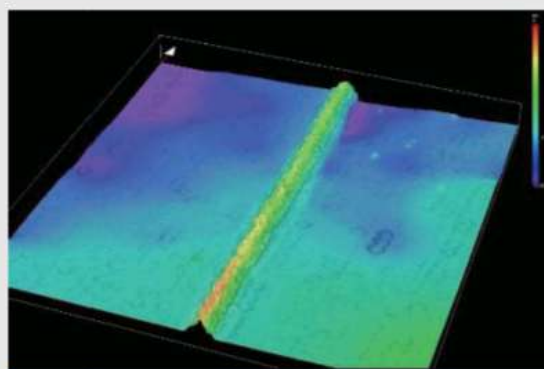
- 适用于TOPCon电池技术路线的背面细栅浆料，适配钢版/PI网版，适配PE/LP/PVD等多种Poly技术路线，可根据背面膜层结构定制
Rear-side finger paste designed for TOPCon cell technology. Compatible with stainless steel stencils / PI screens, and suitable for various Poly-Si deposition routes including PE-CVD, LP-CVD, and PVD. Customizable according to specific rear-side film layer structures.

亮点
Highlights

- 兼容激光/光刻PolyFinger工艺，定制化匹配不同背面膜层结构
Compatible with laser / lithography PolyFinger processes, with customized matching for different rear-side film layer structures.
- 较宽的烧结窗口，在低单耗情况下仍具有优异的电性能及可靠性表现
Wide firing window, delivering excellent electrical performance and reliability even under ultra-low specific consumption (paste usage).
- 良好的有机体系适配超窄线宽钢版/PI网版，具有平整度较优的栅线形貌
Robust organic vehicle system compatible with ultra-narrow line width stainless steel stencils / PI screens, achieving finger profiles with superior flatness and morphology.
- 常规固含及低固含并行，适配客户端不同降本/提效方案
Available in both conventional and low solid content versions, catering to different customer strategies for cost reduction and efficiency improvement.



BSL



GT90系列拥有较优形貌
GT90 Series (Superior morphology)

类型 (Type)	Eta (%)	Uoc (V)	Isc (A)	FF (%)
BSL	/	/	/	/
GT90系列 GT90 Series	0.064	0.0003	0.011	0.12